

Modeling and Simulation of Aerospace Systems Flipped Class: Thermal Domain

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Overview of this presentation

1. Mechanism of Heat Exchange

- Conduction
- Convection
- Radiation

2. Problem Modeling

- Thermal Capacitance
- Static and Dynamic thermal systems
- Biot Number

Introduction

- Thermal systems transfer or store energy via temperature and heat flow.
- Key effects: conduction, convection, radiation, and heat storage.
- Similarities with mechanical, fluid, and electrical systems: Resistance, capacitance, circuit analysis, and dynamic response.
- Unique aspects:
 - Nonlinear, variable-coefficient, distributed-parameter models.
 - No thermal inductance.
- Combination of thermodynamics, fluid mechanics, and heat transfer.
- Simplified analysis using linear, lumped-parameter models.

Conduction: Fourier's Law

The Fourier's law is defined as follows:

$$\frac{Q_h}{A} = -k_{\underline{p},\underline{d},T} \; \underline{\nabla} T$$

Where $k_{p,\underline{d},T}$ is the thermal conductivity. In general, it is a second-order tensor function of: point: p, direction: \underline{d} and temperature: T

- Assuming:Isotropic mediumHomogeneous mediumNo dependance on T

$$k_{\vec{p},\vec{d},T} = k_t = const.$$

By considering only the x direction, Fourier's law becomes:

$$\frac{Q_h}{A} = -k_t \frac{dT}{dx}$$

General Conduction Equation

Considering a closed system with no mechanical work, the First Law of Thermodynamic can be simplified into: $\frac{\partial U}{\partial t} = \sum_{i} Q + U$

$$\frac{\partial U}{\partial t} = \sum_{i} Q_i + U$$

With the Reynold's Transport Theorem, Divergence Theorem and application of the Fourier's Law:

$$\rho c \frac{\partial T}{\partial t} = \nabla \left(k_{\underline{p},\underline{d},T} \nabla T \right) + \frac{U}{V}$$

If the conductivity is a constant:

$$\rho c \frac{\partial T}{\partial t} = k_t \, \nabla^2 T + \frac{U}{V}$$

Includes three second-order space derivatives and a derivative in time.

Conduction for 1D plate and axial rod

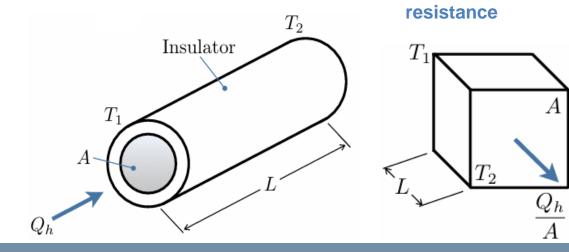
Considering the one-dimensional Fourier's law, assuming costant k_t and uniform Q_h :

$$\frac{Q_h}{A} = -k_t \frac{dT}{dx} \qquad \qquad \int_0^l \frac{Q_h}{A} dx = -\int_{T_1}^{T_2} k_t dT$$

$$\frac{Q_h}{A}L = -k_t(T_2 - T_1) \qquad Q_h = \frac{k_{tA}}{L}\Delta T \qquad \Delta T = \frac{L}{k_t A}Q_h$$
Effort Thermal

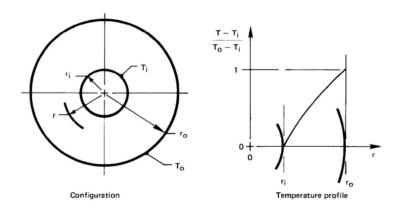
Thermal resistance due to conduction (axial case):

$$R = \frac{L}{k_t A}$$



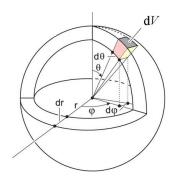
Conduction in Cylindrical and Spherical Coordinates

Thermal resistance due to radial conduction:



$$R = \frac{\ln(r_o/r_i)}{2\pi k_t L}$$

Thermal resistance due to spherical conduction:

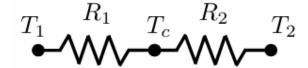


$$R = \frac{r_o - r_i}{4\pi k_t r_o r_i}$$

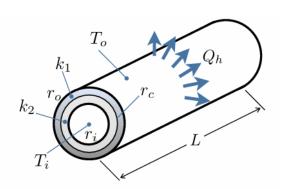
Conduction: resistance modeling

In both cases of radial conduction in a cylinder and axial conduction through a flat plate, it is possible to model the problem considering a series of resistance:

$$T_1 - T_2 = R_{eq}Q_h$$



In which R_{eq} is just the summation of the resistances in series, using the previous formulas depending on the case. For example, considering two different coating materials:



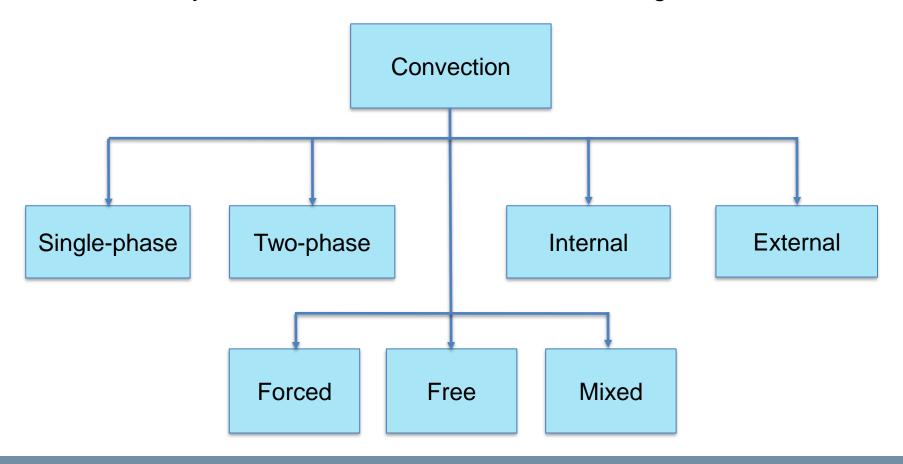
$$R_{eq} = \frac{\ln(r_o/r_c)}{2\pi k_1 L} + \frac{\ln(r_c/r_i)}{2\pi k_2 L}$$

Convection: basics

- Heat transfer by convection occurs when macroscopic mass motion (advection) is present in addition to energy diffusion.
- It is possible only in states of matter that permits internal mass movement, such as fluids (liquids, gases, plasma).
- While convection enhances heat transfer but it also complicates the process significantly more than conduction alone, primarily due to the complexities of fluid dynamics!

Convection: classification

Heat transfer by convection can be **classified** following different lines:



Convection: Newton's law

It is ruled by the **Newton's law:**

$$\frac{Q_h}{A} = h \left(T_s - T_\infty \right)$$

Where:

- T_s is the temperature of the surface of the solid
- T_{∞} is the temperature of the free-steam fluid
- Convection coefficient h is a function of:
 - fluid properties (thermal conductivity, density, specific heat)
 - o fluid velocity field
 - o area of the solid-fluid interface across which heat transfer occurs

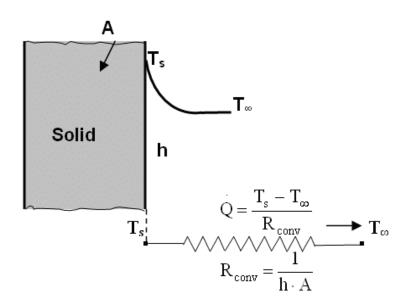
$$h = h \left(c_{Pf}, \rho_f, \mu_f, \lambda_f, D_C, \frac{w}{g \rho_{f0} k_{Pf} (T_f - T_w)} \right)$$

Typically, the computation of h requires detailed CFD approach or experiments

Convective Resistance

Thermal resistance due to convection:

$$R = \frac{1}{hA}$$



Conditions of heat transfer	$h\left[W/(m^2K)\right]$
Gases in free convection	2-20
Liquids in free convection	50-1000
Gases in forced convection	25-300
Liquid in forced convection	1000-40000

Radiation: black body

Stefan-Boltzman Law for an ideal black body:

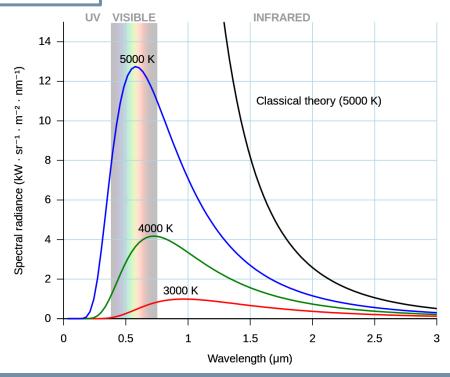
$$\frac{Q_h}{A} = \sigma T^4$$

Where
$$\sigma = 5.67 \times 10^{-8} \ \frac{W}{m^2 K^4}$$

Where a black body is an ideal body that:

- absorbs all incident radiation, regardless of frequency.
- if at thermal equilibrium, emits thermal radiation at every frequency isotropically.

In particular, a black body emits depending on its temperature, as shown on the right.



Radiation: gray opaque body

Stefan-Boltzman Law for a gray opaque body:

$$\frac{Q_h}{A} = \varepsilon \, \sigma \, T^4$$

Where ε is the **emissivity** which defines how much a surface differs from a **black** body. By definition, a black body in **thermal equilibrium** has an ε =1.

From balance of energy:

$$\alpha + \rho + \tau = 1$$

Where

α: Absorbivity

ρ: Reflectivity

τ: Transmissivity

Kirchhoff's law:

$$\alpha = \varepsilon$$

Thermal Capacitance

Thermal capacitance is the measurable physical quantity that characterizes the amount of heat required to change a substance's temperature by a given amount:

$$C = \frac{Q}{\Delta T} = \left[\frac{kJ}{kg\ K}\right]$$

C can be also defined as the product of the specific heat capacity per mass unit and the mass of the object.

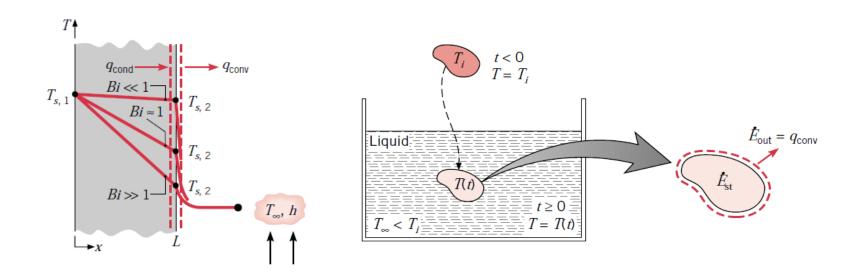
$$Q_h = MC_p \frac{dT}{dt} \qquad \qquad C = MC_p$$

Static vs Dynamic

Aspect	Static Thermal Analysis	Dynamic Thermal Analysis
Capacitance	Low storage	High storage
Modeling	Algebraic Equations	Diffusion equation (2nd- order PDE)
Modeling approach	Simple laws of	Lumped-parameter modeling possible (ODEs)
Capacitance model	conduction, convection and radiation	Single or multiple- lumped models depending on convection and conduction

Biot Number

When temperature gradients within the solid may be neglected?



Biot Number

Biot Number:
$$B_i = \frac{Thermal\ resistance\ for\ conduction\ inside\ a\ body}{Thermal\ resistance\ for\ convection\ on\ the\ surface} = \frac{h\ L_C}{k}$$

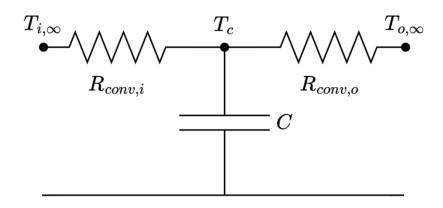
Where L_C is a characteristic length (thickness for flat plate, diameter/6 for sphere, thickness/2 for a fin and diameter/4 for a long cylinder).

If B _i < 0.1	If B _i > 0.1
Conduction negligible compared to convection	Conduction not negligible
Thermal gradient inside body negligible	Thermal gradient inside body not negligible
Single-lumped capacitance modeling	Multiple-lumped capacitance modeling

Case: $B_i < 0.1$

Single lumped capacitance:

- Temperature gradient in solid negligible
- Model with single lumped capacitance, heat capacity of solid and convection heat transfer

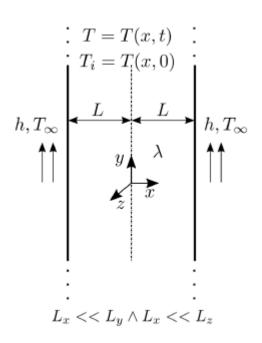


From energy balance on the internal node, the solution is the following first-order ODE:

$$MC_p \frac{dT_c}{dt} + 2T_c hA = hA(T_{i,\infty} + T_{o,\infty})$$

Case: $B_i > 0.1$

1D Transient Analysis:



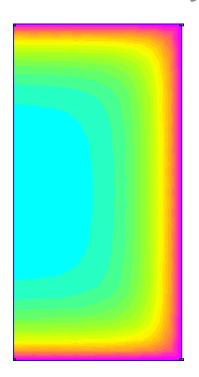
Cartesian coord.

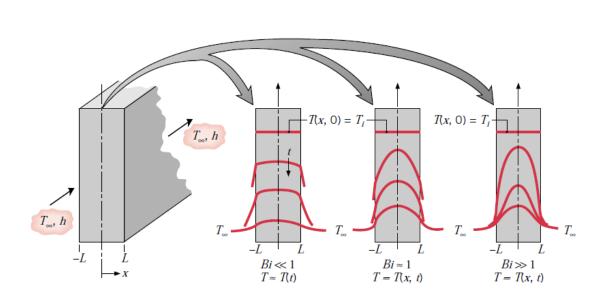
$$\theta(\tilde{x}, \mathsf{Fo}) = \sum_{n=1}^{\infty} C_n \exp(-\lambda_n^2 \mathsf{Fo}) \cos(\lambda_n \tilde{x})$$

$$C_n = \frac{4 \sin \lambda_n}{2\lambda_n + \sin(2\lambda_n)}$$
$$\lambda_n \tan \lambda_n = \text{Bi}$$

Case: $B_i > 0.1$

1D Transient Analysis:

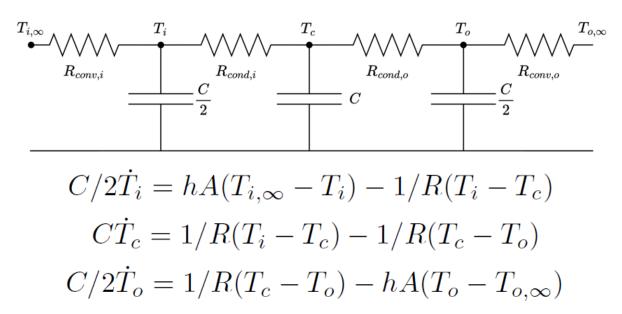




Case: $B_i > 0.1$

Multiple-lumped capacitance modeling:

- Conduction resistance present
- Multiple capacitance lumps
- Thermal properties assumed homogeneous
- Large Biot number requires division into several nodes



Biot Number

The Biot number could be generalized, by redefining h depending on mechanisms of thermal energy transport:

$$h_{cond} = \frac{1}{R_{cond}} = \frac{k}{L}$$

$$h_{conv} = f(N_u, R_e, P_r)$$

$$h_{rad} = \epsilon \sigma (T_w^2 + T_r^2)(T_w + T_r)$$

Bibliography

- Guilizzoni Manfredo Heat Transfer and Thermal Analysis notes;
- John H. Lienhard IV A Heat Transfer Notebook;
- Frank P.Incropera Fundamentals of Heat and Mass Transfer.